

ISL9V3040D3S / ISL9V3040S3S / ISL9V3040P3

EcoSPARK™ 300mJ, 400V, N-Channel Ignition IGBT

General Description

The ISL9V3040D3S, ISL9V3040S3S, and ISL9V3040P3 are the next generation ignition IGBTs that offer outstanding SCIS capability in the space saving D-Pak (TO-252), as well as the industry standard D²-Pak (TO-263), and TO-220 plastic packages. This device is intended for use in automotive ignition circuits, specifically as a coil driver. Internal diodes provide voltage clamping without the need for external components.

EcoSPARK™ devices can be custom made to specific clamp voltages. Contact your nearest Fairchild sales office for more information.

Formerly Developmental Type 49362

Applications

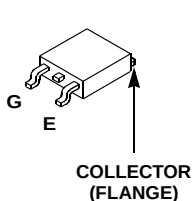
- Automotive Ignition Coil Driver Circuits
- Coil- On Plug Applications

Features

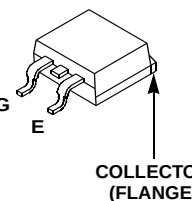
- Space saving D-Pak package availability
- SCIS Energy = 300mJ at $T_J = 25^\circ\text{C}$
- Logic Level Gate Drive

Package

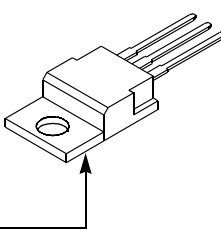
JEDEC TO-252AA
D-Pak



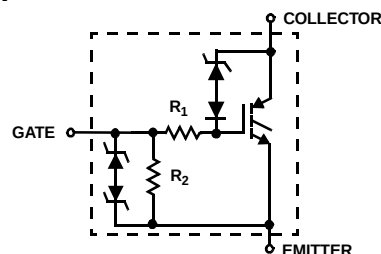
JEDEC TO-263AB
D²-Pak



JEDEC TO-220AB



Symbol



Device Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
BV_{CER}	Collector to Emitter Breakdown Voltage ($I_C = 1 \text{ mA}$)	430	V
BV_{ECS}	Emitter to Collector Voltage - Reverse Battery Condition ($I_C = 10 \text{ mA}$)	24	V
E_{SCIS25}	At Starting $T_J = 25^\circ\text{C}$, $I_{SCIS} = 14.2\text{A}$, $L = 3.0 \text{ mHy}$	300	mJ
$E_{SCIS150}$	At Starting $T_J = 150^\circ\text{C}$, $I_{SCIS} = 10.6\text{A}$, $L = 3.0 \text{ mHy}$	170	mJ
I_{C25}	Collector Current Continuous, At $T_C = 25^\circ\text{C}$, See Fig 9	21	A
I_{C110}	Collector Current Continuous, At $T_C = 110^\circ\text{C}$, See Fig 9	17	A
V_{GEM}	Gate to Emitter Voltage Continuous	± 10	V
P_D	Power Dissipation Total $T_C = 25^\circ\text{C}$	150	W
	Power Dissipation Derating $T_C > 25^\circ\text{C}$	1.0	W/ $^\circ\text{C}$
T_J	Operating Junction Temperature Range	-40 to 175	$^\circ\text{C}$
T_{STG}	Storage Junction Temperature Range	-40 to 175	$^\circ\text{C}$
T_L	Max Lead Temp for Soldering (Leads at 1.6mm from Case for 10s)	300	$^\circ\text{C}$
T_{pkg}	Max Lead Temp for Soldering (Package Body for 10s)	260	$^\circ\text{C}$
ESD	Electrostatic Discharge Voltage at 100pF, 1500Ω	4	kV

Package Marking and Ordering Information

Device Marking	Device	Package	Tape Width	Quantity
V3040D	ISL9V3040D3S	TO-252AA	16mm	2500
V3040S	ISL9V3040S3S	TO-263AB	24mm	800
V3040P	ISL9V3040P3	TO-220AB	-	-

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units	
Off State Characteristics							
BV _{CER}	Collector to Emitter Breakdown Voltage	I _C = 2mA, V _{GE} = 0, R _G = 1KΩ, See Fig. 15 T _J = -40 to 150°C	370	400	430	V	
BV _{CES}	Collector to Emitter Breakdown Voltage	I _C = 10mA, V _{GE} = 0, R _G = 0, See Fig. 15 T _J = -40 to 150°C	390	420	450	V	
BV _{ECS}	Emitter to Collector Breakdown Voltage	I _C = -75mA, V _{GE} = 0V, T _C = 25°C	30	-	-	V	
BV _{GES}	Gate to Emitter Breakdown Voltage	I _{GES} = ± 2mA	±12	±14	-	V	
I _{CER}	Collector to Emitter Leakage Current	V _{CER} = 250V, R _G = 1KΩ, See Fig. 11	T _C = 25°C	-	-	25	μA
		T _C = 150°C	-	-	1	mA	
I _{ECS}	Emitter to Collector Leakage Current	V _{EC} = 24V, See Fig. 11	T _C = 25°C	-	-	1	mA
			T _C = 150°C	-	-	40	mA
R ₁	Series Gate Resistance		-	70	-	Ω	
R ₂	Gate to Emitter Resistance		10K	-	26K	Ω	

On State Characteristics

$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	$I_C = 6\text{A}$, $V_{GE} = 4\text{V}$	$T_C = 25^\circ\text{C}$, See Fig. 3	-	1.25	1.60	V
$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	$I_C = 10\text{A}$, $V_{GE} = 4.5\text{V}$	$T_C = 150^\circ\text{C}$, See Fig. 4	-	1.58	1.80	V
$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	$I_C = 15\text{A}$, $V_{GE} = 4.5\text{V}$	$T_C = 150^\circ\text{C}$	-	1.90	2.20	V

Dynamic Characteristics

$Q_{G(ON)}$	Gate Charge	$I_C = 10A, V_{CE} = 12V,$ $V_{GE} = 5V, \text{ See Fig. 14}$		-	17	-	nC
$V_{GE(TH)}$	Gate to Emitter Threshold Voltage	$I_C = 1.0mA,$ $V_{CE} = V_{GE},$ See Fig. 10	$T_C = 25^{\circ}C$	1.3	-	2.2	V
			$T_C = 150^{\circ}C$	0.75	-	1.8	V
V_{GEP}	Gate to Emitter Plateau Voltage	$I_C = 10A,$ $V_{CE} = 12V$		-	3.0	-	V

Switching Characteristics

$t_{d(ON)R}$	Current Turn-On Delay Time-Resistive	$V_{CE} = 14\text{V}$, $R_L = 1\Omega$, $V_{GE} = 5\text{V}$, $R_G = 1\text{K}\Omega$, $T_J = 25^\circ\text{C}$, See Fig. 12	-	0.7	4	μs
t_{rR}	Current Rise Time-Resistive		-	2.1	7	μs
$t_{d(OFF)L}$	Current Turn-Off Delay Time-Inductive	$V_{CE} = 300\text{V}$, $L = 500\mu\text{H}$, $V_{GE} = 5\text{V}$, $R_G = 1\text{K}\Omega$, $T_J = 25^\circ\text{C}$, See Fig. 12	-	4.8	15	μs
t_{fL}	Current Fall Time-Inductive		-	2.8	15	μs
SCIS	Self Clamped Inductive Switching	$T_J = 25^\circ\text{C}$, $L = 3.0\text{mH}$, $R_G = 1\text{K}\Omega$, $V_{GE} = 5\text{V}$, See Fig. 1 & 2	-	-	300	mJ

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction-Case	TO-252, TO-263, TO-220	-	-	1.0	$^\circ\text{C/W}$
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Typical Performance Curves (Continued)

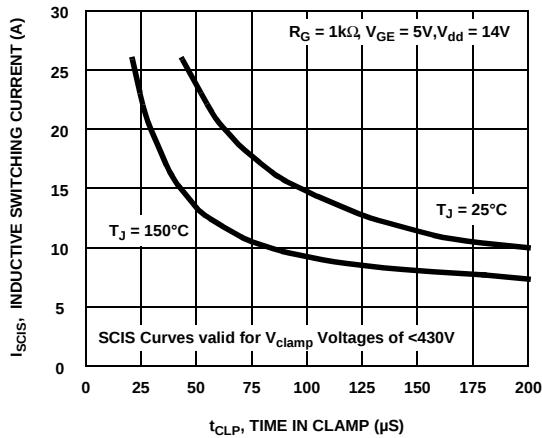


Figure 1. Self Clamped Inductive Switching Current vs Time in Clamp

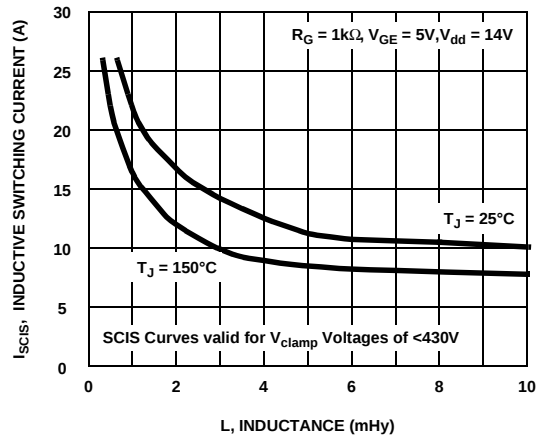


Figure 2. Self Clamped Inductive Switching Current vs Inductance

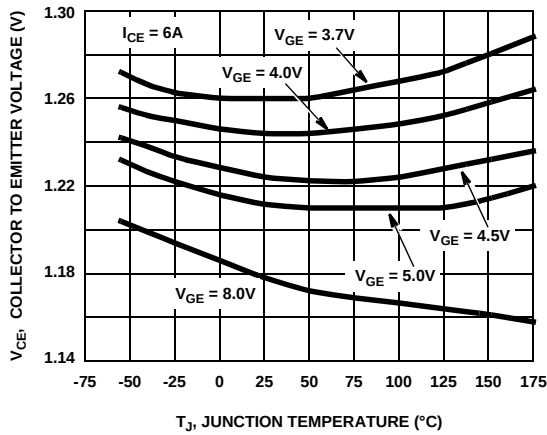


Figure 3. Collector to Emitter On-State Voltage vs Junction Temperature

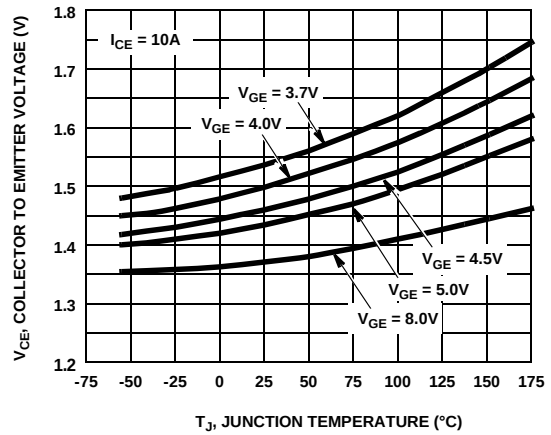


Figure 4. Collector to Emitter On-State Voltage vs Junction Temperature

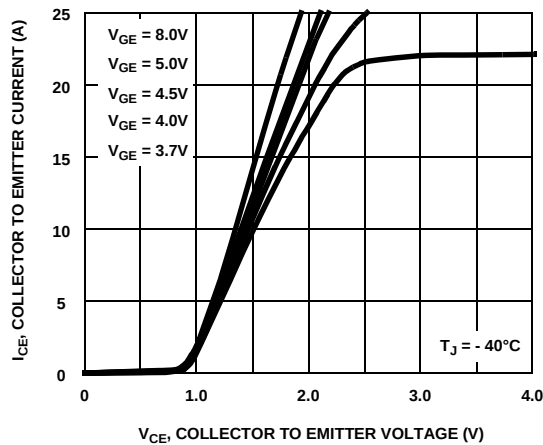


Figure 5. Collector to Emitter On-State Voltage vs Collector Current

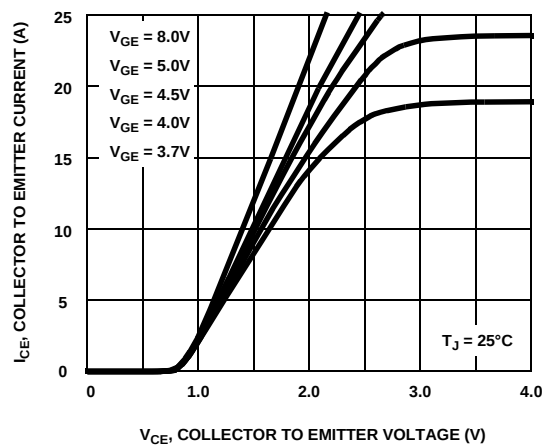


Figure 6. Collector to Emitter On-State Voltage vs Collector Current

Typical Performance Curves (Continued)

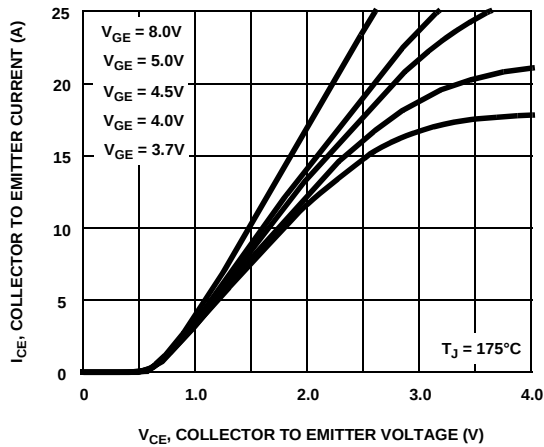


Figure 7. Collector to Emitter On-State Voltage vs Collector Current

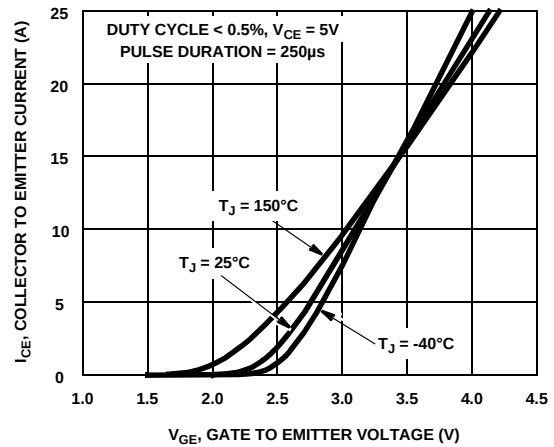


Figure 8. Transfer Characteristics

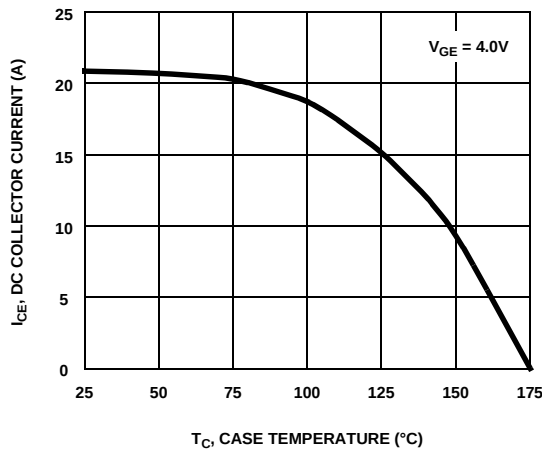


Figure 9. DC Collector Current vs Case Temperature

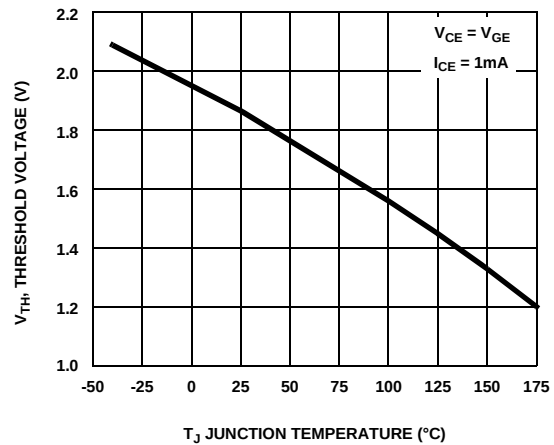


Figure 10. Threshold Voltage vs Junction Temperature

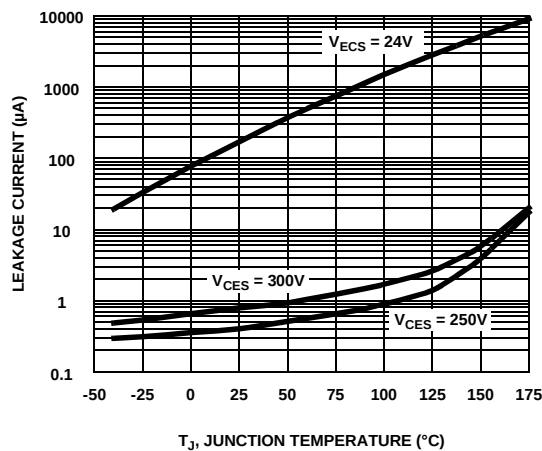


Figure 11. Leakage Current vs Junction Temperature

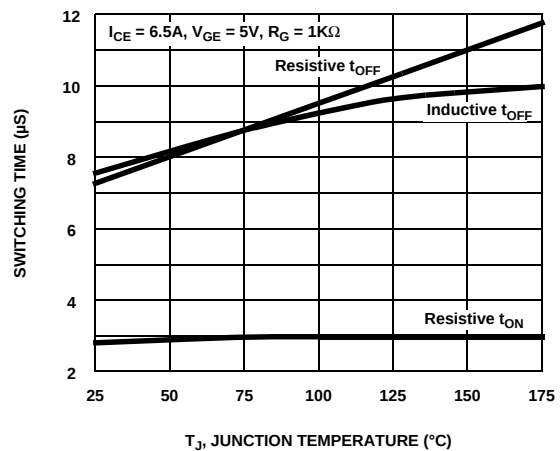


Figure 12. Switching Time vs Junction Temperature

Typical Performance Curves (Continued)

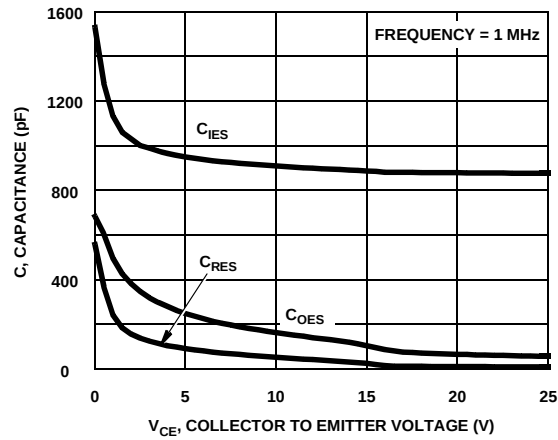


Figure 13. Capacitance vs Collector to Emitter Voltage

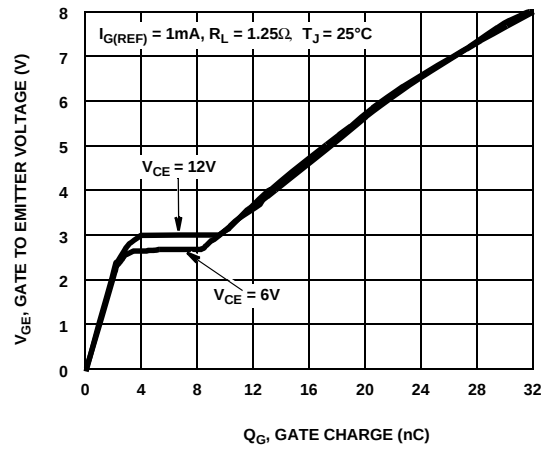


Figure 14. Gate Charge

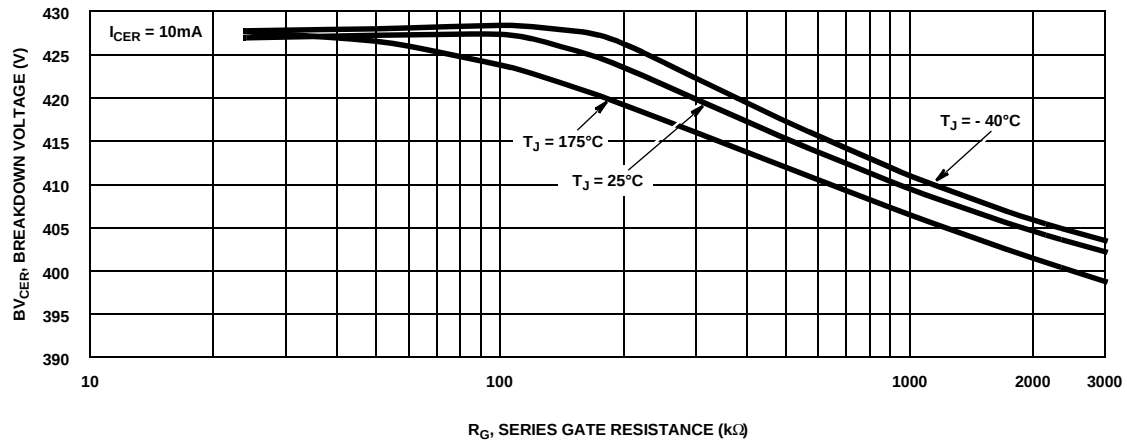


Figure 15. Breakdown Voltage vs Series Gate Resistance

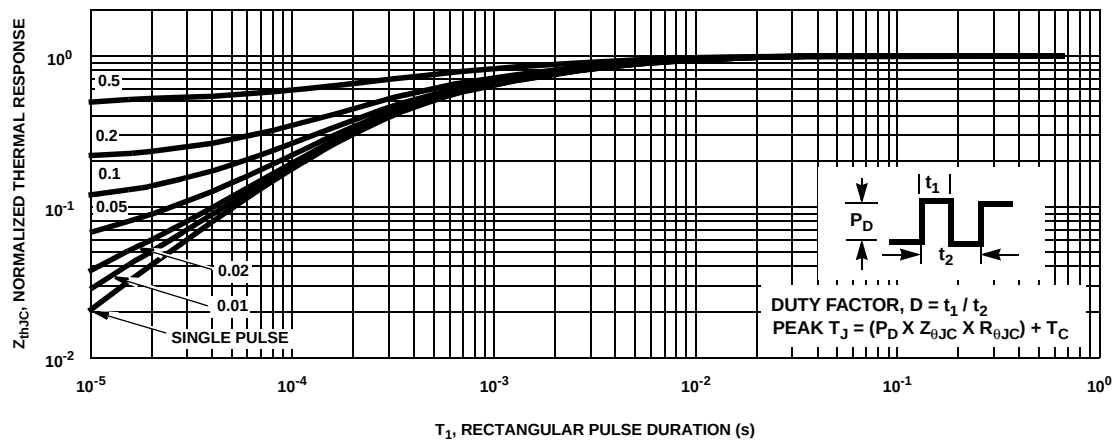


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case

Test Circuit and Waveforms

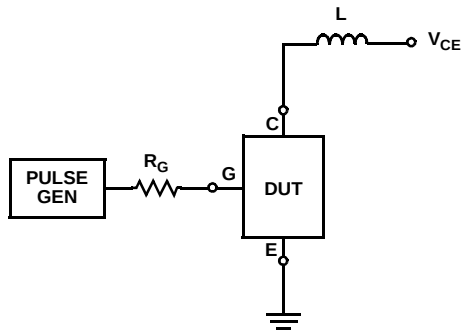


Figure 17. Inductive Switching Test Circuit

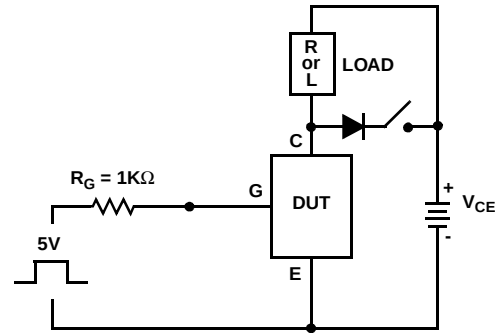


Figure 18. t_{ON} and t_{OFF} Switching Test Circuit

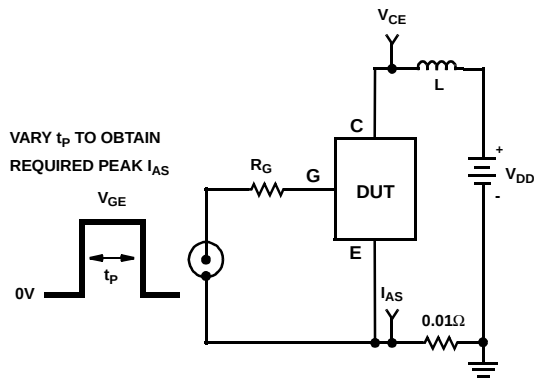


Figure 19. Unclamped Energy Test Circuit

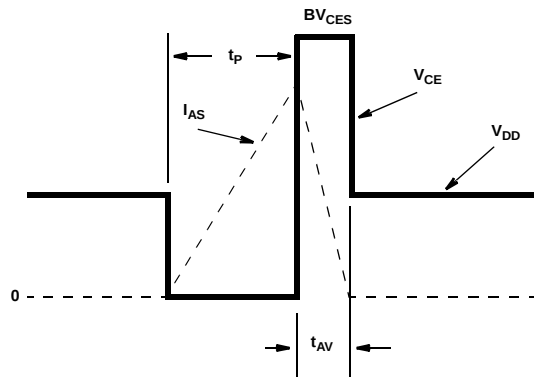


Figure 20. Unclamped Energy Waveforms

SPICE Thermal Model

REV 25 May 2001

ISL9V3040D3S / ISL9V3040S3S / ISL9V3040P3

CTHERM1 th 6 2.5e -4
CTHERM2 6 5 2.5e -3
CTHERM3 5 4 1.6e -3
CTHERM4 4 3 1.3e -2
CTHERM5 3 2 6.1e -3
CTHERM6 2 tl 9.9e +2

RTHERM1 th 6 1.2e -1
RTHERM2 6 5 1.9e -1
RTHERM3 5 4 2.2e -1
RTHERM4 4 3 6.0e -2
RTHERM5 3 2 5.8e -2
RTHERM6 2 tl 1.6e -4

SABER Thermal Model

SABER thermal model

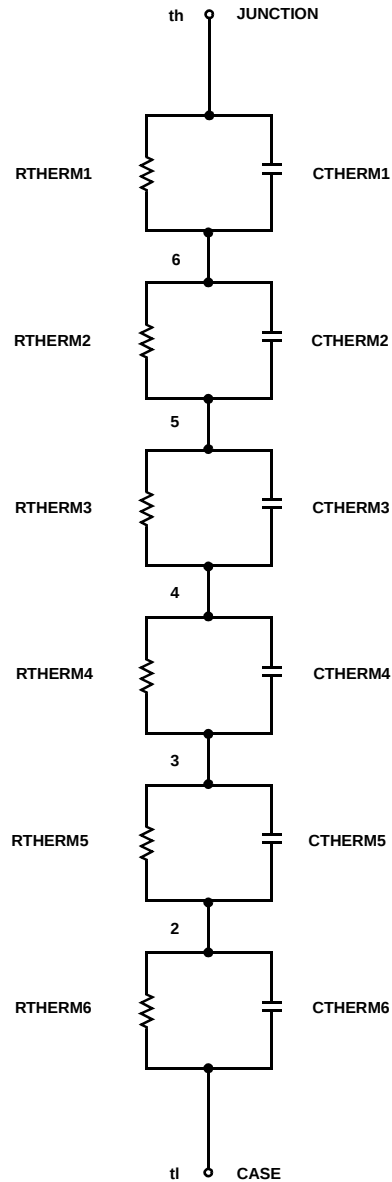
ISL9V3040D3S / ISL9V3040S3S / ISL9V3040P3

template thermal_model th tl
thermal_c th, tl

```
{
  ctherm.ctherm1 th 6 = 2.5e -4
  ctherm.ctherm2 6 5 = 2.5e -3
  ctherm.ctherm3 5 4 = 1.6e -3
  ctherm.ctherm4 4 3 = 1.3e -2
  ctherm.ctherm5 3 2 = 6.1e -3
  ctherm.ctherm6 2 tl = 9.9e +2

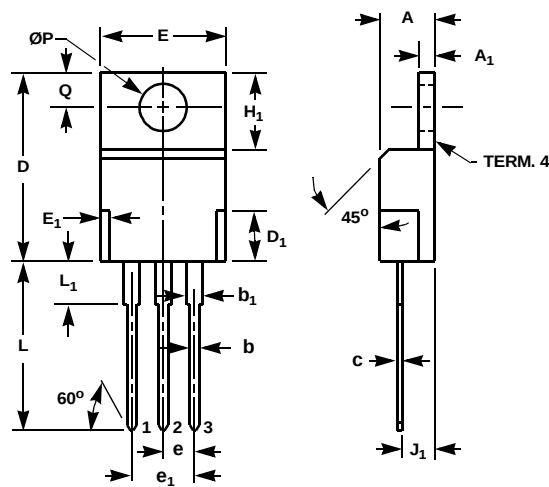
```

```
rtherm.rtherm1 th 6 = 1.2e -1
rtherm.rtherm2 6 5 = 1.9e -1
rtherm.rtherm3 5 4 = 2.2e -1
rtherm.rtherm4 4 3 = 6.0e -2
rtherm.rtherm5 3 2 = 5.8e -2
rtherm.rtherm6 2 tl = 1.6e -4
}
```



TO-220AA

3 LEAD JEDEC TO-220AB PLASTIC PACKAGE

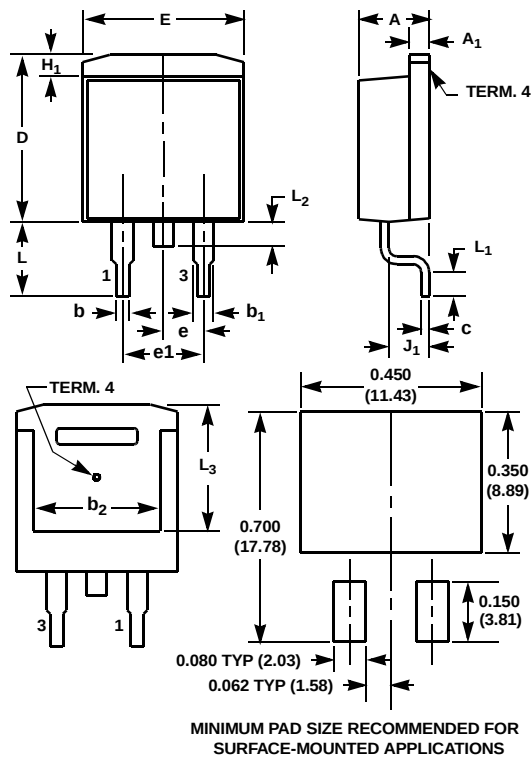


SYMBOL	INCHES		MILLIMETERS		NOTE
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A ₁	0.048	0.052	1.22	1.32	-
b	0.030	0.034	0.77	0.86	3, 4
b ₁	0.045	0.055	1.15	1.39	2, 3
c	0.014	0.019	0.36	0.48	2, 3, 4
D	0.590	0.610	14.99	15.49	-
D ₁	-	0.160	-	4.06	-
E	0.395	0.410	10.04	10.41	-
E ₁	-	0.030	-	0.76	-
e	0.100 TYP		2.54 TYP		5
e ₁	0.200 BSC		5.08 BSC		5
H ₁	0.235	0.255	5.97	6.47	-
J ₁	0.100	0.110	2.54	2.79	6
L	0.530	0.550	13.47	13.97	-
L ₁	0.130	0.150	3.31	3.81	2
ØP	0.149	0.153	3.79	3.88	-
Q	0.102	0.112	2.60	2.84	-

ISL9V3040D3S / ISL9V3040S3S / ISL9V3040P3

TO-263AB

SURFACE MOUNT JEDEC TO-263AB PLASTIC PACKAGE



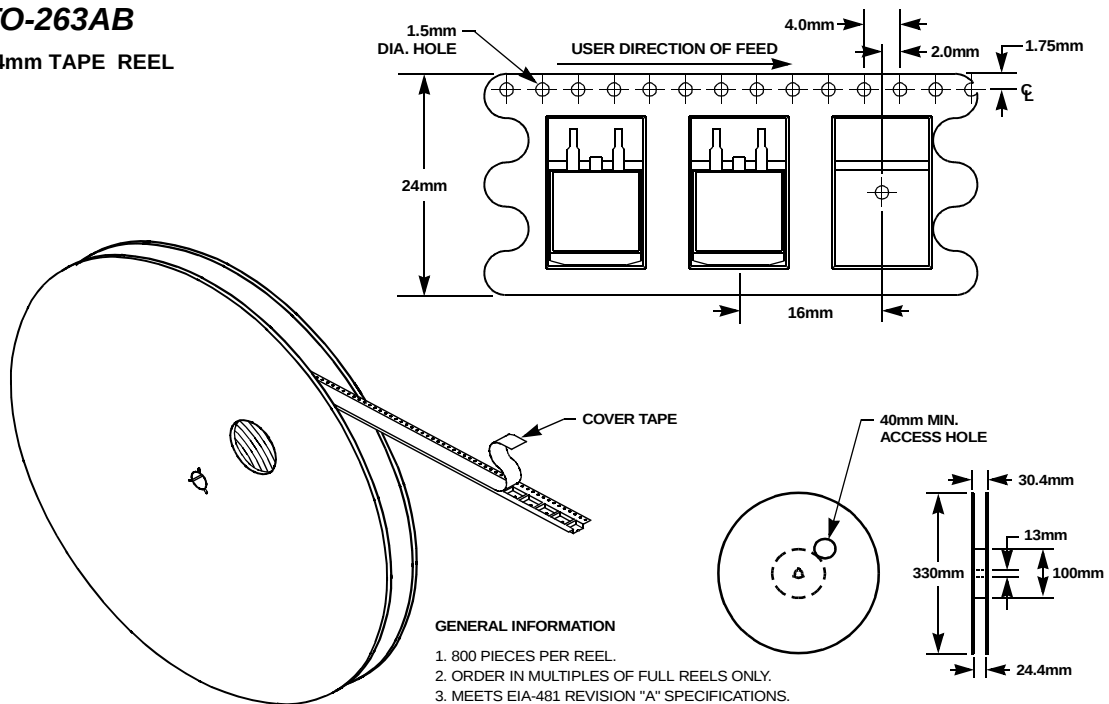
SYMBOL	INCHES		MILLIMETERS		NOTE
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A ₁	0.048	0.052	1.22	1.32	4, 5
b	0.030	0.034	0.77	0.86	4, 5
b ₁	0.045	0.055	1.15	1.39	4, 5
b ₂	0.310	-	7.88	-	2
c	0.018	0.022	0.46	0.55	4, 5
D	0.405	0.425	10.29	10.79	-
E	0.395	0.405	10.04	10.28	-
e	0.100 TYP		2.54 TYP		7
e ₁	0.200 BSC		5.08 BSC		7
H ₁	0.045	0.055	1.15	1.39	-
J ₁	0.095	0.105	2.42	2.66	-
L	0.175	0.195	4.45	4.95	-
L ₁	0.090	0.110	2.29	2.79	4, 6
L ₂	0.050	0.070	1.27	1.77	3
L ₃	0.315	-	8.01	-	2

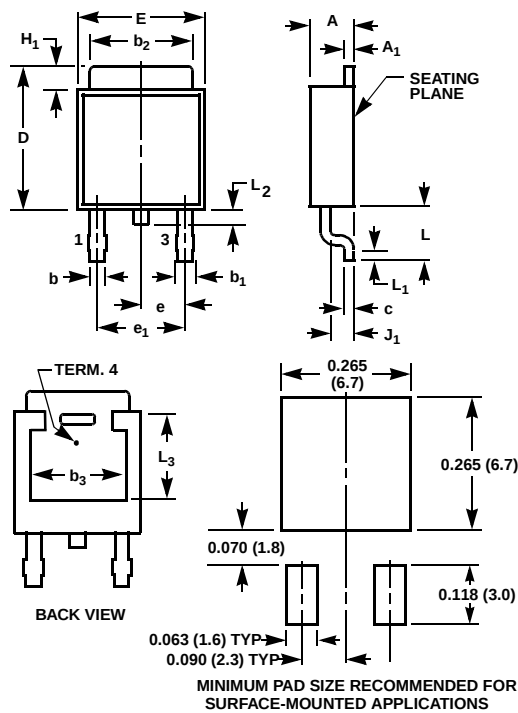
NOTES:

1. These dimensions are within allowable dimensions of Rev. C of JEDEC TO-263AB outline dated 2-92.
2. L₃ and b₂ dimensions established a minimum mounting surface for terminal 4.
3. Solder finish uncontrolled in this area.
4. Dimension (without solder).
5. Add typically 0.002 inches (0.05mm) for solder plating.
6. L₁ is the terminal length for soldering.
7. Position of lead to be measured 0.120 inches (3.05mm) from bottom of dimension D.
8. Controlling dimension: Inch.
9. Revision 11 dated 5-99.

TO-263AB

24mm TAPE REEL

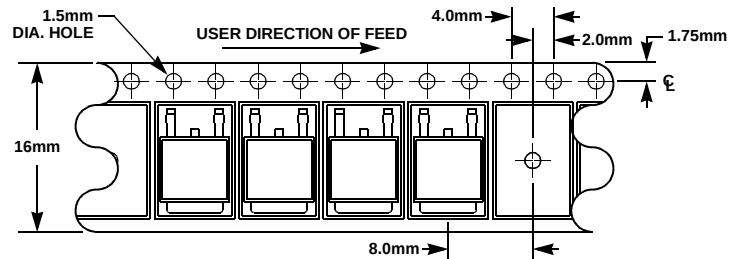
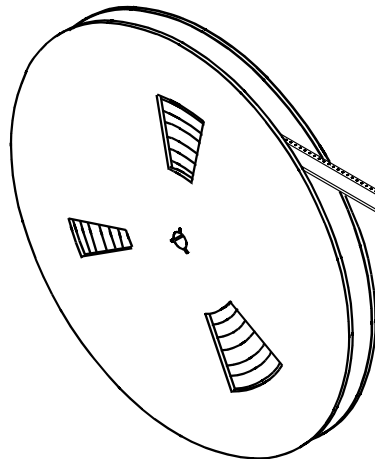


TO-252AA**SURFACE MOUNT JEDEC TO-252AA PLASTIC PACKAGE**

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.086	0.094	2.19	2.38	-
A_1	0.018	0.023	0.46	0.58	4, 5
b	0.028	0.033	0.72	0.84	4, 5
b_1	0.033	0.045	0.84	1.14	4
b_2	0.205	0.215	5.21	5.46	4, 5
b_3	0.190	-	4.83	-	2
c	0.018	0.023	0.46	0.58	4, 5
D	0.270	0.295	6.86	7.49	-
E	0.250	0.265	6.35	6.73	-
e	0.090 TYP		2.28 TYP		7
e_1	0.180 BSC		4.57 BSC		7
H_1	0.035	0.050	0.89	1.27	-
J_1	0.040	0.045	1.02	1.14	-
L	0.100	0.115	2.54	2.92	-
L_1	0.020	-	0.51	-	4, 6
L_2	0.025	0.040	0.64	1.01	3
L_3	0.170	-	4.32	-	2

NOTES:

1. These dimensions are within allowable dimensions of Rev. B of JEDEC TO-252AA outline dated 9-88.
2. L_3 and b_3 dimensions establish a minimum mounting surface for terminal 4.
3. Solder finish uncontrolled in this area.
4. Dimension (without solder).
5. Add typically 0.002 inches (0.05mm) for solder plating.
6. L_1 is the terminal length for soldering.
7. Position of lead to be measured 0.090 inches (2.28mm) from bottom of dimension D.
8. Controlling dimension: Inch.
9. Revision 12 dated 5-00.

TO-252AA**16mm TAPE REEL****GENERAL INFORMATION**

1. 2500 PIECES PER REEL.
2. ORDER IN MULTIPLES OF FULL REELS ONLY.
3. MEETS EIA-481 REVISION "A" SPECIFICATIONS.

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CoolFET™	FRFET™	PACMAN™	Stealth™	
CROSSVOLT™	GlobalOptoisolator™	POP™	SuperSOT™-3	
DenseTrench™	GTO™	Power247™	SuperSOT™-6	
DOME™	HiSeC™	PowerTrench [®]	SuperSOT™-8	
EcoSPARK™	ISOPLANAR™	QFET™	SyncFET™	
E ² CMOS™	LittleFET™	QS™	TinyLogic™	
Ensigna™	MicroFET™	QTOptoelectronics™	TruTranslation™	
FACT™	MicroPak™	Quiet Series™	UHC™	
FACTQuietSerie™	MICROWIRE™	SILENT SWITCHER [®]	UltraFET [®]	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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